Kulicke & Soffa Introduces New Offerings at SEMICON China 2018

SINGAPORE--(BUSINESS WIRE)--Mar. 9, 2018-- Kulicke & Soffa Industries, Inc. (NASDAQ: KLIC) (“Kulicke & Soffa”, “K&S” or the “Company”) will be showcasing newly launched equipment and marketing leading packaging solutions during SEMICON China 2018 trade show at Shanghai New International Expo Center (SNIEC) in Shanghai from March 14 to 16.

The latest range of solutions, RAPID™ Pro *GEN-S* (Smart) *Series* ball bonder and OptoLux™ ball bonder for LED will be featured at the SEMICON China trade show. The RAPID™ Pro introduces advanced process capabilities with real-time monitoring and diagnostics to ensure highest yield, while the high speed OptoLux™ is set to revolutionize the wire bonding in LED market focusing on ease-of-use with recommended start-up parameters to facilitate process optimization. In addition to these, the Company will be demonstrating capabilities of its high performance APAMA™ DA die attach, latest multifunctional iFlex T2 equipment, together with its broad range of aftermarket products and services comprise of spares, consumables, software, repair and refurbishment services.

Hoang Huy Hoang, Kulicke & Soffa’s Senior Vice President of Global Sales & Aftermarket Products and Services Business Unit, said, “The semiconductor market continues to evolve rapidly with increasing demand of highly complex and more integrated packaging technologies. Apart from providing our customers with innovative and high-performance equipment to address these challenges, we want to extend our support through a full range of aftermarket solutions to improve uptime, enhance asset utilization and augment fleet and process management.”

Customers can see the full assembly of solutions at the SEMICON China trade show in Shanghai, China, Hall N3, Booth #3409.

About Kulicke & Soffa

Kulicke & Soffa (NASDAQ: KLIC) is a leading provider of semiconductor packaging and electronic assembly solutions supporting the global automotive, consumer, communications, computing and industrial segments. As a pioneer in the semiconductor space, K&S has provided customers with market leading packaging solutions for decades. In recent years, K&S has expanded its product offerings through strategic acquisitions and organic development, adding advanced packaging, electronics assembly, wedge bonding and a broader range of expendable tools to its core offerings. Combined with its extensive expertise in process technology and focus on development, K&S is well positioned to help customers meet the challenges of packaging and assembling the next-generation of electronic devices. (www.kns.com)

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Kulicke & Soffa Industries, Inc.
Marilyn Sim
Public Relations
P: +65-6880-9309
F: +65-6880-9580
msim@kns.com
or
Joseph Elgindy
Investor Relations & Strategic Initiatives
P: +1-215-784-7500
F: +1-215-784-6180
investor@kns.com
